

A/58140

10/399469

DT09 Rec'd PCT/PTO 18 APR 2003

FORM 1595

08-18-2003

U.S. DEPARTMENT OF COMMERCE  
Patent and Trademark Office



ET

102526915

To the Honorable Commissioner of Patents and Trademarks. Please record the attached original documents or copy thereof.

1. Name of conveying party(ies): 4-18-03  
Toshiaki MORITA  
Additional name(s) of conveying party(ies) attached?  Yes  No

2. Name and address of receiving party(ies):  
NAME: Shima Seiki Mfg., Ltd.  
  
ADDRESS: 85, Sakata, Wakayama-shi  
Wakayama 651-8511 Japan  
  
Additional name(s) & addresses(es) attached?  
 Yes  No

3. Name of Conveyance:  
 Assignment  Merger  
 Security Agreement  Change of Name  
 Other  
Execution/Effective Date: April 9, 2003

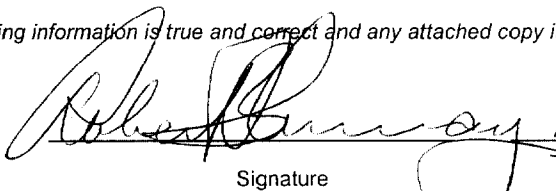
4. Application number(s) or patent number(s): 10399469  
If this document is being filed together with a new application, the execution date of the application is: April 9, 2003  
A. Patent Application No.(s)  
New Application (PCT/JPOI/09057)  
B. Patent No.(s)  
Additional numbers attached?  Yes  No

5. Name and address of party to whom correspondence concerning document should be mailed:  
Name:  
Internal Address: Rothwell, Figg, Ernst & Manbeck  
Suite 800  
Street Address: 1425 K St., N.W.  
City: Washington,  
State: D.C. Zip: 20005  
Telephone No.: 202/783-6040  
Facsimile No.: 202/783-6031  
Attorney Docket No.: 2933-0146

6. Total number of applications and patents involved: 1  
7. Total fee (37 CFR 3.41): . . . \$ 40  
 Enclosed  
 Authorized to be charged to deposit account  
8. Deposit account number: 02-2135  
Attach duplicate copy of this page if paying by deposit account

40.00 OF

DO NOT USE THIS SPACE

9. Statement and signature.  
*To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.*  
Robert B. Murray  April 18, 2003  
Name of Person Signing Signature Date

Total number of pages including cover sheet, attachments and documents: 2

**ASSIGNMENT OF PATENT APPLICATION**

**WHEREAS, I/We** Toshiaki MORITA, a citizen of Japan,  
*First Named Inventor*  
residing at 116, Yoshino, Nokami-cho, Kaiso-gun, Wakayama 640-1103 Japan,  
*Address*

\_\_\_\_\_, a citizen of \_\_\_\_\_,  
*Second named Inventor, if any*  
residing at \_\_\_\_\_,  
*Address*

\_\_\_\_\_, a citizen of \_\_\_\_\_,  
*Third Named Inventor, if any*  
residing at \_\_\_\_\_,  
*Address*

\_\_\_\_\_, a citizen of \_\_\_\_\_,  
*Fourth Named Inventor, if any*  
residing at \_\_\_\_\_,  
*Address*

**ASSIGNOR(S)**, am/are the inventor(s) of an invention in (insert title) COMPOUND NEEDLE

for which I/we have executed an application for Letters Patent of the United States,

of even date herewith;

(Check One)  U.S. Serial Number \_\_\_\_\_ filed \_\_\_\_\_;  
 International Application No PCT/ \_\_\_\_\_ filed \_\_\_\_\_;

and

**WHEREAS,** SHIMA SEIKI MFG., LTD. 85, Sakata, Wakayama-shi, Wakayama 641-8511 Japan  
*Assignee* *Citizenship or Corporate Situs* *Address*

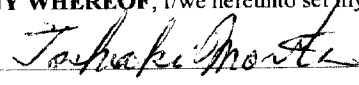
**ASSIGNEE**, is desirous of obtaining the entire right, title and interest in, to and under the said invention and the said application;

**NOW, THEREFORE**, in consideration of the sum of One Dollar (\$1.00) to me/us in hand paid, and other good and valuable consideration, the receipt of which is hereby acknowledged, I/we, the said **ASSIGNOR(S)** have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said **ASSIGNEE**, its successors, legal representatives and assigns, the entire right, title and interest in, to and under the said invention, and the said application and all divisions, renewals and continuations thereof, and all Letters Patent of the United States which may be granted thereon and all reexamination certificates, reissues and extensions thereof, and I/we hereby authorize and request the Commissioner of Patents of the United States, to issue all Letters Patent for said invention to the said **ASSIGNEE**, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

**AND I/WE HEREBY** covenant that I/we have the full right to convey the entire interest herein assigned, and that I/we have not executed, and will not execute, any agreement in conflict herewith.

**AND I/WE HEREBY** further covenant and agree that I/we will communicate to said **ASSIGNEE**, its successors, legal representatives and assigns, any facts known to me/us respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and generally do everything possible to aid the said **ASSIGNEE**, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention at the expense of the **ASSIGNEE**.

**IN TESTIMONY WHEREOF**, I/we hereunto set my/our hand(s) and seal(s) the day and year set opposite my/our signature(s).

(Toshiaki MORITA)  L.S. Date 9 Apr, 2003  
\_\_\_\_\_  
L.S. Date \_\_\_\_\_, 20\_\_\_\_  
\_\_\_\_\_  
L.S. Date \_\_\_\_\_, 20\_\_\_\_  
\_\_\_\_\_  
L.S. Date \_\_\_\_\_, 20\_\_\_\_

Witness:

\_\_\_\_\_  
*Name* *Date*  
\_\_\_\_\_  
*Name* *Date*

Foreign Inventor Sole/Joint Assignment